

- Member of Texas Instruments' Widebus+™ Family
- 5-Ω Switch Connection Between Two Ports
- TTL-Compatible Input Levels
- Flow-Through Architecture Optimizes PCB Layout
- I<sub>off</sub> Supports Partial-Power-Down Mode Operation
- Latch-Up Performance Exceeds 100 mA Per JESD 78, Class II
- ESD Protection Exceeds JESD 22
  - 2000-V Human-Body Model (A114-A)
  - 200-V Machine Model (A115-A)
  - 1000-V Charged-Device Model (C101)

## description

The SN74CBT34X245 provides 32 bits of high-speed TTL-compatible bus switching. The low on-state resistance of the switch allows connections to be made with minimal propagation delay.

The device is organized as four 8-bit bus switches, two 16-bit bus switches, or one 32-bit bus switch. When output enable ( $\overline{OE}$ ) is low, the switch is on, and port A is connected to port B. When  $\overline{OE}$  is high, the switch is open, and the high-impedance state exists between the two ports.

This device is fully specified for partial-power-down applications using I<sub>off</sub>. The I<sub>off</sub> circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

## DBB PACKAGE (TOP VIEW)

NC	1	80	V <sub>CC</sub>
1A1	2	79	$\overline{1OE}$
1A2	3	78	1B1
1A3	4	77	1B2
1A4	5	76	1B3
1A5	6	75	1B4
1A6	7	74	1B5
1A7	8	73	1B6
1A8	9	72	1B7
GND	10	71	1B8
NC	11	70	V <sub>CC</sub>
2A1	12	69	$\overline{2OE}$
2A2	13	68	2B1
2A3	14	67	2B2
2A4	15	66	2B3
2A5	16	65	2B4
2A6	17	64	2B5
2A7	18	63	2B6
2A8	19	62	2B7
GND	20	61	2B8
NC	21	60	V <sub>CC</sub>
3A1	22	59	$\overline{3OE}$
3A2	23	58	3B1
3A3	24	57	3B2
3A4	25	56	3B3
3A5	26	55	3B4
3A6	27	54	3B5
3A7	28	53	3B6
3A8	29	52	3B7
GND	30	51	3B8
NC	31	50	V <sub>CC</sub>
4A1	32	49	$\overline{4OE}$
4A2	33	48	4B1
4A3	34	47	4B2
4A4	35	46	4B3
4A5	36	45	4B4
4A6	37	44	4B5
4A7	38	43	4B6
4A8	39	42	4B7
GND	40	41	4B8

NC – No internal connection



Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

Widebus+ is a trademark of Texas Instruments.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



POST OFFICE BOX 655303 • DALLAS, TEXAS 75265

Copyright © 2001, Texas Instruments Incorporated

# SN74CBT34X245 32-BIT FET BUS SWITCH

SCDS089C – MAY 1999 – REVISED MAY 2001

## ORDERING INFORMATION

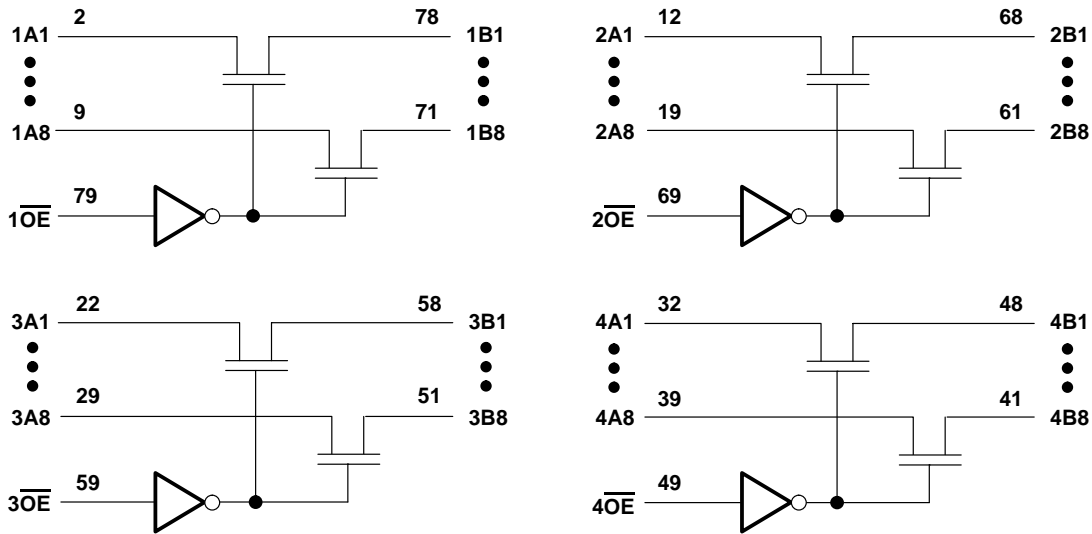
T <sub>A</sub>	PACKAGE†	ORDERABLE PART NUMBER	TOP-SIDE MARKING
–40°C to 85°C	TVSOP – DBB   Tape and reel	SN74CBT34X245DBBR	CBT34X245

† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at [www.ti.com/sc/package](http://www.ti.com/sc/package).

FUNCTION TABLE  
(each 8-bit bus switch)

INPUT OE	FUNCTION
L	A port = B port
H	Disconnect

## logic diagram (positive logic)



## absolute maximum ratings over operating free-air temperature range (unless otherwise noted)‡

Supply voltage range, V <sub>CC</sub>	–0.5 V to 7 V
Input voltage range, V <sub>I</sub> (see Note 1)	–0.5 V to 7 V
Continuous channel current	128 mA
Input clamp current, I <sub>IK</sub> (V <sub>I/O</sub> < 0)	–50 mA
Package thermal impedance, θ <sub>JA</sub> (see Note 2)	64°C/W
Storage temperature range, T <sub>stg</sub>	–65°C to 150°C

‡ Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.  
2. The package thermal impedance is calculated in accordance with JESD 51-7.

**recommended operating conditions (see Note 3)**

	MIN	MAX	UNIT
V <sub>CC</sub> Supply voltage	4	5.5	V
V <sub>IH</sub> High-level control input voltage	2		V
V <sub>IL</sub> Low-level control input voltage		0.8	V
T <sub>A</sub> Operating free-air temperature	-40	85	°C

NOTE 3: All unused control inputs of the device must be held at V<sub>CC</sub> or GND to ensure proper device operation. Refer to TI application report *Implications of Slow or Floating CMOS Inputs*, literature number SCBA004.

**electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)**

PARAMETER	TEST CONDITIONS	MIN	TYP†	MAX	UNIT
V <sub>IK</sub>	V <sub>CC</sub> = 4.5 V, I <sub>I</sub> = -18 mA			-1.2	V
I <sub>I</sub>	V <sub>CC</sub> = 5.5 V, V <sub>I</sub> = 5.5 V or GND			±5	μA
I <sub>off</sub>	V <sub>CC</sub> = 0, V <sub>I</sub> or V <sub>O</sub> = 0 to 5.5 V			10	μA
I <sub>CC</sub>	V <sub>CC</sub> = 5.5 V, I <sub>O</sub> = 0, V <sub>I</sub> = V <sub>CC</sub> or GND			6	μA
ΔI <sub>CC</sub> ‡	Control inputs V <sub>CC</sub> = 5.5 V, One input at 3.4 V, Other inputs at V <sub>CC</sub> or GND			3.5	mA
C <sub>i</sub>	Control inputs V <sub>I</sub> = 3 V or 0		3.5		pF
C <sub>io(OFF)</sub>	V <sub>O</sub> = 3 V or 0, $\overline{OE} = V_{CC}$		5.5		pF
r <sub>on</sub> §	V <sub>CC</sub> = 4 V, TYP at V <sub>CC</sub> = 4 V	V <sub>I</sub> = 2.4 V, I <sub>I</sub> = 15 mA	11	17	Ω
	V <sub>CC</sub> = 4.5 V	V <sub>I</sub> = 0, I <sub>I</sub> = 64 mA	5	7	
		I <sub>I</sub> = 30 mA	5	7	
		V <sub>I</sub> = 2.4 V, I <sub>I</sub> = 15 mA	8	13	

† All typical values are at V<sub>CC</sub> = 5 V (unless otherwise noted), T<sub>A</sub> = 25°C.

‡ This is the increase in supply current for each input that is at the specified TTL voltage level rather than V<sub>CC</sub> or GND.

§ Measured by the voltage drop between the A and B terminals at the indicated current through the switch. On-state resistance is determined by the lower of the voltages of the two (A or B) terminals.

**switching characteristics over recommended operating free-air temperature range, C<sub>L</sub> = 50 pF (unless otherwise noted) (see Figure 1)**

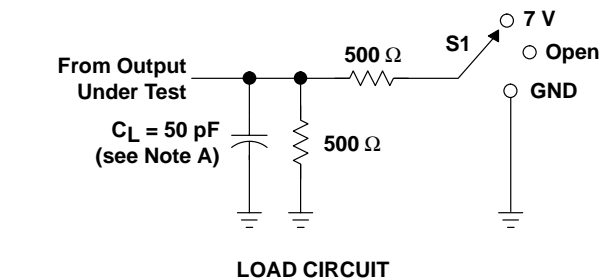
PARAMETER	FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 4 V		V <sub>CC</sub> = 5 V ± 0.5 V		UNIT
			MIN	MAX	MIN	MAX	
t <sub>pd</sub> ¶	A or B	B or A			0.25		ns
t <sub>en</sub>	$\overline{OE}$	A or B	2.2	6.5	1.9	6	ns
t <sub>dis</sub>	$\overline{OE}$	A or B	1.9	6.2	2.2	6.7	ns

¶ The propagation delay is the calculated RC time constant of the typical on-state resistance of the switch and the specified load capacitance, when driven by an ideal voltage source (zero output impedance).

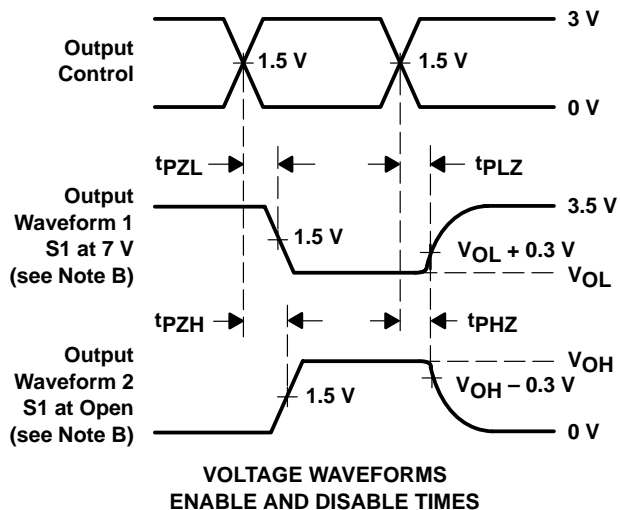
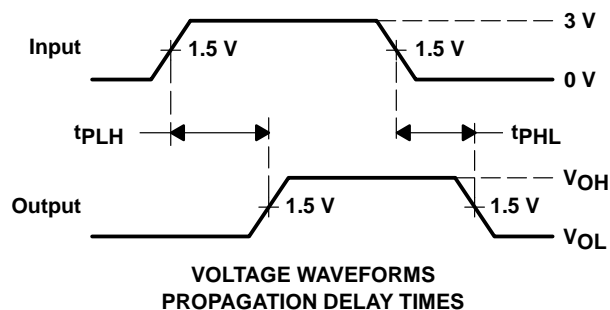
# SN74CBT34X245 32-BIT FET BUS SWITCH

SCDS089C – MAY 1999 – REVISED MAY 2001

## PARAMETER MEASUREMENT INFORMATION



TEST	S1
$t_{pd}$	Open
$t_{PLZ}/t_{PZL}$	7 V
$t_{PHZ}/t_{PZH}$	Open



- NOTES:
- $C_L$  includes probe and jig capacitance.
  - Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
  - All input pulses are supplied by generators having the following characteristics:  $PRR \leq 10 \text{ MHz}$ ,  $Z_O = 50 \Omega$ ,  $t_r \leq 2.5 \text{ ns}$ ,  $t_f \leq 2.5 \text{ ns}$ .
  - The outputs are measured one at a time with one transition per measurement.
  - $t_{PLZ}$  and  $t_{PHZ}$  are the same as  $t_{dis}$ .
  - $t_{PZL}$  and  $t_{PZH}$  are the same as  $t_{en}$ .
  - $t_{PLH}$  and  $t_{PHL}$  are the same as  $t_{pd}$ .

Figure 1. Load Circuit and Voltage Waveforms

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead finish/ Ball material (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
SN74CBT34X245DBBR	ACTIVE	TSSOP	DBB	80	2000	RoHS & Green	NIPDAU	Level-1-260C-UNLIM	-40 to 85	CBT34X245	Samples

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSOLETE:** TI has discontinued the production of the device.

(2) **RoHS:** TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

**RoHS Exempt:** TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

**Green:** TI defines "Green" to mean the content of Chlorine (Cl) and Bromine (Br) based flame retardants meet JS709B low halogen requirements of <=1000ppm threshold. Antimony trioxide based flame retardants must also meet the <=1000ppm threshold requirement.

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "-" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

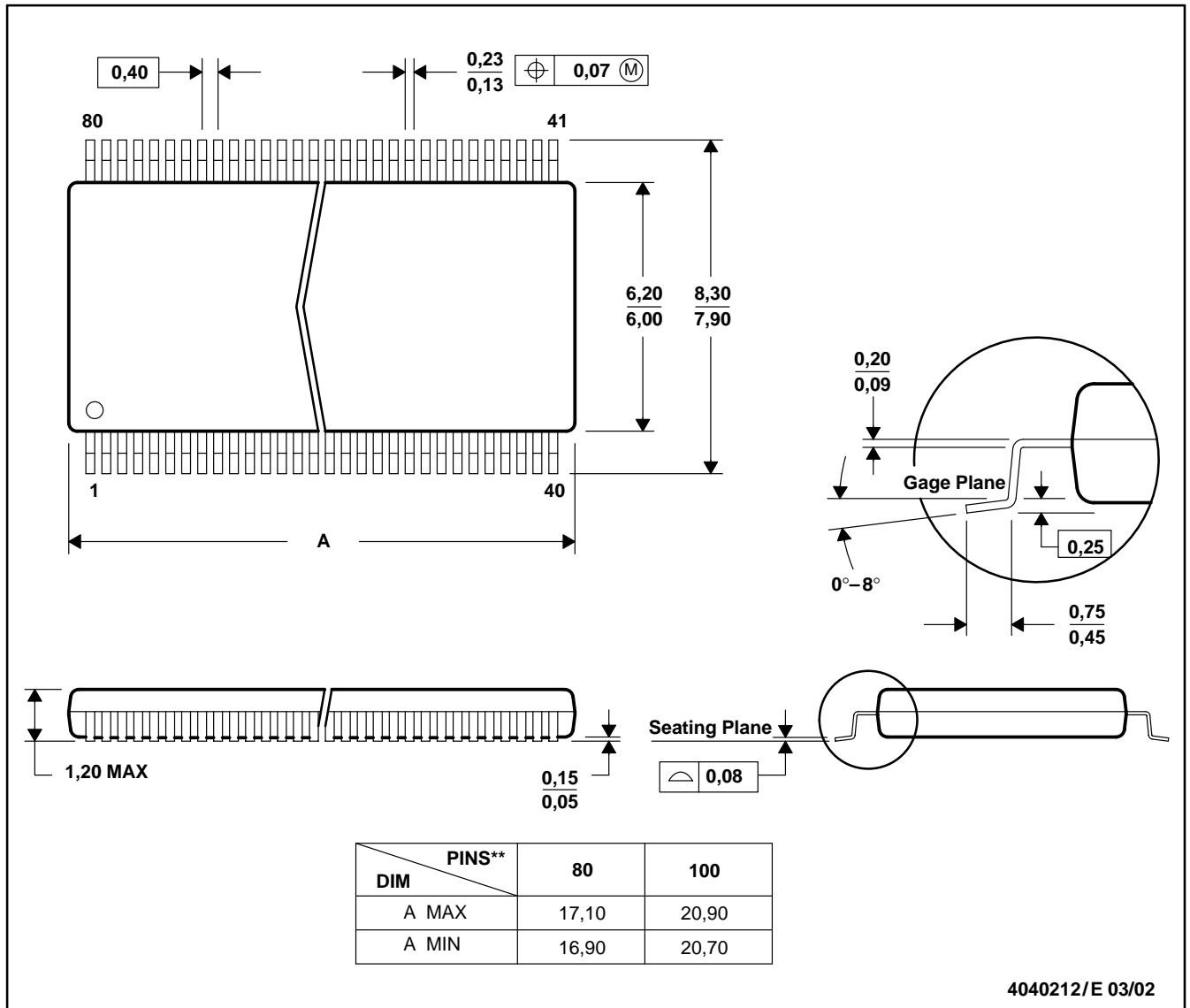
**Important Information and Disclaimer:**The information provided on this page represents TI's knowledge and belief as of the date that it is provided. TI bases its knowledge and belief on information provided by third parties, and makes no representation or warranty as to the accuracy of such information. Efforts are underway to better integrate information from third parties. TI has taken and continues to take reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

DBB (R-PDSO-G\*\*)

PLASTIC SMALL-OUTLINE PACKAGE

80 PINS SHOWN



- NOTES: A. All linear dimensions are in millimeters.  
 B. This drawing is subject to change without notice.  
 C. Falls within JEDEC : 80 Pin – MO-153 Variation FF  
 100 Pin – MO-194 Variation BB

## IMPORTANT NOTICE AND DISCLAIMER

TI PROVIDES TECHNICAL AND RELIABILITY DATA (INCLUDING DATASHEETS), DESIGN RESOURCES (INCLUDING REFERENCE DESIGNS), APPLICATION OR OTHER DESIGN ADVICE, WEB TOOLS, SAFETY INFORMATION, AND OTHER RESOURCES "AS IS" AND WITH ALL FAULTS, AND DISCLAIMS ALL WARRANTIES, EXPRESS AND IMPLIED, INCLUDING WITHOUT LIMITATION ANY IMPLIED WARRANTIES OF MERCHANTABILITY, FITNESS FOR A PARTICULAR PURPOSE OR NON-INFRINGEMENT OF THIRD PARTY INTELLECTUAL PROPERTY RIGHTS.

These resources are intended for skilled developers designing with TI products. You are solely responsible for (1) selecting the appropriate TI products for your application, (2) designing, validating and testing your application, and (3) ensuring your application meets applicable standards, and any other safety, security, or other requirements. These resources are subject to change without notice. TI grants you permission to use these resources only for development of an application that uses the TI products described in the resource. Other reproduction and display of these resources is prohibited. No license is granted to any other TI intellectual property right or to any third party intellectual property right. TI disclaims responsibility for, and you will fully indemnify TI and its representatives against, any claims, damages, costs, losses, and liabilities arising out of your use of these resources.

TI's products are provided subject to TI's Terms of Sale (<https://www.ti.com/legal/termsofsale.html>) or other applicable terms available either on [ti.com](https://www.ti.com) or provided in conjunction with such TI products. TI's provision of these resources does not expand or otherwise alter TI's applicable warranties or warranty disclaimers for TI products.

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265  
Copyright © 2021, Texas Instruments Incorporated